	© Copyright 2005. I international and Pa	Dosition Dec IPC, Bannockb n-American co	c laration ourn, Illinois. A opyright conver	ll rights reserved untions.	under both	This docume level parts, t	ent is a declara	ation of encon	f the substances npasses all lowe	s within the er level ma	e manufactur terials for wi	er listed i hich the r	tem. Note nanufactu	e: if the item is arer has engine	s an asseml ering resp	oly with lowe onsibility.	
1752-21.1	.1 IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x				Form Type Distribute						eous Materi	Interials and Mfg Information					
Supplie	r Information																
Company name* Co				Company unique ID			Unique ID Authority					Response Date*					
onsemi												2024-05-18					
Contact N	Jame		Title - Contact				Phone - Contact*				Email - Contact*						
Product-	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
Authorize	ed Representative*	Title - Representative				Phone - Representative*				Email - Representative*							
Product-	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
	Requester Item Number Mfr Item		Number Mfr Item Name			<u>.</u>	Effective Date Version Manufacturing Site			ring Site	Weight*		UOM		Unit Type		
	MUR115		5				2024-05-18						250.82	mg		Each	
Manufa	cturing Proccess Informa	tion															
	Terminal Plating / Grid Array Material			Ferminal Base Alloy J-STD-020 MSL			Peak Process Body Temperature Max Time a			ime at Peak	eak Temperature Number of Reflow Cycles						
			CU Alloy				C 30				seconds 3						
Comments	8																
For more	information regarding material	composition	please refer to	page 3													

RoHS Material Composition Declaration			Declaration Type *	Detailed	
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et	
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).		
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the
Supplier Digital Signature	astislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

	cable [E] enter the weigh			ance category (JIG or Requester) or enter a [F] Optionally enter the positive (+) and n				
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.18	mg	Supplier	Silicon (Si)	7440-21-3		0.18	mg
Die Attach Solder	7.98	mg	Supplier	Silver (Ag)	7440-22-4		0.1995	mg
			А	Lead (Pb)	7439-92-1	7a	7.3815	mg
			Supplier	Tin (Sn)	7440-31-5		0.399	mg
Lead Frame	125.08	mg	Supplier	Copper (Cu)	7440-50-8		125.08	mg
Mold Compound-Black	116.8	mg		Metal Hydroxide	proprietary data		5.84	mg
			Supplier	Carbon Black (C)	1333-86-4		1.168	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		87.6	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		11.68	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		10.512	mg
Plating	0.78	mg	Supplier	Tin (Sn)	7440-31-5		0.78	mg